

HVD350B

Variable Capacitance Diode for VCO

REJ03G0497-0100

(Previous: ADE-208-848)

Rev.1.00 Jan 20, 2005

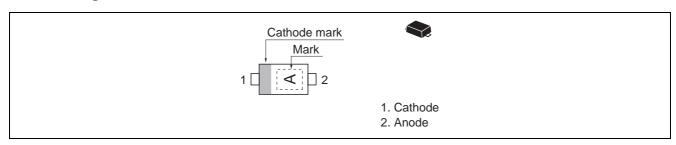
Features

- High capacitance ratio. (n = 2.80 min)
- Low series resistance. (rs = $0.50 \Omega \text{ max}$)
- Good C-V linearity.
- Super small Flat Lead Package (SFP) is suitable for surface mount design.

Ordering Information

Type No.	Laser Mark	Package Code
HVD350B	A	SFP

Pin Arrangement



Absolute Maximum Ratings

 $(Ta = 25^{\circ}C)$

Item	Symbol	Value	Unit
Reverse voltage	V_R	15	V
Junction temperature	Tj	125	°C
Storage temperature	Tstg	−55 to +125	°C

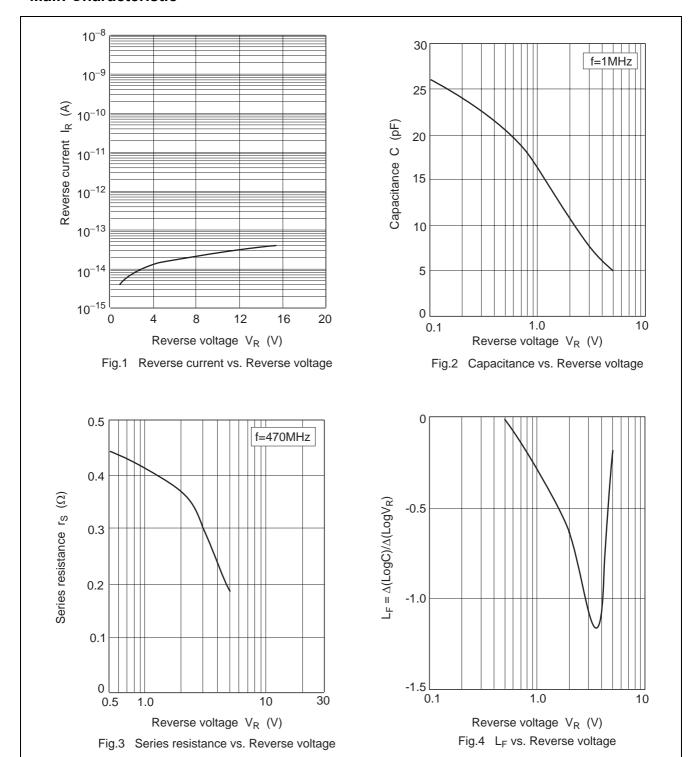
Electrical Characteristics

 $(Ta = 25^{\circ}C)$

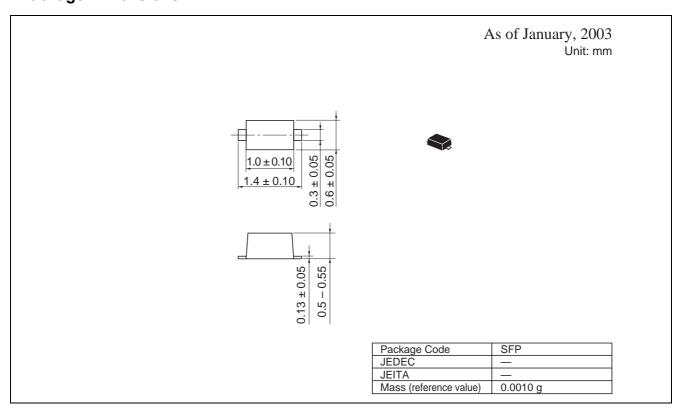
Item	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse current	I _{R1}	_	_	10	nA	V _R = 15 V
	I _{R2}	_	_	100		V _R = 15 V, Ta = 60°C
Capacitance	C ₁	15.50	_	17.00	pF	V _R = 1 V, f = 1 MHz
	C ₄	5.00	_	6.00		V _R = 4 V, f = 1 MHz
Capacitance ratio	n	2.80	_	_	_	C ₁ / C ₄
Series resistance	rs	_	_	0.50	Ω	V _R = 1 V, f = 470 MHz

Note: 1. Please do not use the soldering iron due to avoid high stress to the SFP package.

Main Characteristic



Package Dimensions



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Renesas Technology Singapore Pte. Ltd.
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